



Evyap Sabun Malaysia Sdn Bhd

Evyap Oleo HPST

Hydrogenated Refined Bleached Deodorized Palm Stearin (HRBDPS)

Product Data Sheet

CAS No. 68514 -74 - 9

EINECS No. 917 – 090-0

Parameter	Unit	Specification
Appearance at 30 Deg. C	-	White bulk or flake or bead form, free of foreign matter.
Colour, Lovibond, Max	In 5, ¼" Cell	Y=30.0; R= 3.0
Free Fatty Acid as Palmitic	%	0.3 Max.
Acid Value	mg KOH/Gm	0.7 Max
Sap. Value	mg KOH/Gm	198 - 206
Iodine Value	Gm I ₂ / 100 Gm	0.5 Max.

Fatty Acid Composition	Unit	Specification
C 12	% by GC	2.0 Max.
C 14	% by GC	3.0 Max.
C 16	% by GC	53 - 65
C 18	% by GC	35 - 45
C 18:1	% by GC	1.0 Max.
Others	% by GC	1.0 Max.

The above chart indicates typical available specifications. Customised specifications are also available.

APPLICATIONS

Preparation of Margarine, food ingredients, cosmetics and personal care products.

PACKING

Available in road tanker or bulk ISO container loads. Customised packing size can be made available upon request.

BEST BEFORE

6 months from the date of manufacturing in original containers, stored under standard conditions.

CERTIFICATIONS

This product is Kosher certified by OK Kosher Certification (USA) & Halal certified by JAKIM (MALAYSIA). This product is manufactured in facility certified as per ISO 9001:2015, FSSC 22000, GMP+B2 by Lloyd's Register Quality Assurance and RSPO Supply Chain MB Certification Standard certified by SIRIM (MALAYSIA), Certificate Number: RSPO-SC 00157.

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